

# CALL FOR ABSTRACTS

Abstract Submission Deadline Extension:

November 15, 2020

The 13th International Conference on the Technology of Plasticity (ICTP 2021)

July 25-30, 2021 • The Ohio State University
Ohio Union • Columbus, Ohio, USA



Note, this call for abstracts is reopened for the 13th ICTP, originally planned for 2020 and now set for 2021.

From fundamental science to industrial application, the breadth of the metal forming community will convene at The 13th International Conference on the Technology of Plasticity (ICTP 2021). Scientists and engineers from across industry, academia, and government will share their latest improvements and innovations in all aspects of metal forming science and technology, with the intent of facilitating linkages and collaborations among these groups.

## DON'T MISS THIS OPPORTUNITY TO LEARN FROM AND CONNECT WITH LEADERS IN METAL FORMING.

This conference will provide a forum for presentations and discussions on all areas related to the plastic deformation of materials to create components. Topics of particular interest include, but are not limited to:

- Metal Forming Processes & Equipment
- Joining by Forming and Deformation
- Microstructure and Damage Development & Characterization
- Big Data and Metal Forming
- High Speed and Impulse Forming
- Agile Metal Forming
- Microstructure Development by Forming
- Technologies to Speed Innovation
- Value of, and Limits to, Simulation

Learn more about technical topics planned for this congress at www.tms.org/ICTP2021.

#### **CONFERENCE ORGANIZERS:**

#### **Lead Organizer**

**Glenn Daehn**, The Ohio State University, USA

#### **Local Organizing Committee**

**Libby Culley**, The Ohio State University, USA

**Glenn Daehn**, The Ohio State University, USA

**Anupam Vivek**, The Ohio State University, USA

### **Advisory Committee**

**Jian Cao**, Northwestern University, USA

**Glenn Daehn**, The Ohio State University, USA

**Brad Kinsey**, University of New Hampshire, USA

**Erman Tekkaya**, Technical University of Dortmund, Germany

**Yoshinori Yoshida**, Gifu University, Japan

**SUBMIT YOUR ABSTRACT BY NOVEMBER 15, 2020 AT:** 

www.tms.org/ICTP2021